

Soldering Instructions for Applied Geomechanics 5-Pin Tilt Sensors

Our 5-pin biaxial tilt sensors require tinning before wires are attached or the sensors are soldered into a PC board. The following tinning procedure should be used:

1. Melt solder at 265°C (approx. 500°F) in a solder pot.
2. Dip electrodes in Kester 2331 flux.
3. Immerse electrodes in the solder pot for no more than 3 seconds.
4. Allow sensor and electrodes to cool, then clean off flux with water.

When soldering to the tinned electrodes, the soldering iron tip temperature should be set at 500°F. The maximum recommended time of contact between the tip and an electrode is 3 seconds.

When soldering the sensor onto a PC board, we recommend soldering the center pin first. The sensor should be supported so that it remains flush with the PC board surface during soldering.



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